



Material Composition Sheet

Product: GS1522-CQR
 Package Type: DQFP-128 Pin (66/tray)
 Manufacturer: Gennum Corporation

Date: 06-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		10.50	Al	0.06	0.57	5714
			Si	10.44	99.42	994286
			Sub-total:	10.50	99.99	1000000
Die Attach	8360	3.80	Ag	2.85	75.00	750000
			Curing agent & hardener	0.19	5.00	50000
			Epoxy Resin	0.76	20.00	200000
			Sub-total:	3.80	100.00	1000000
Lead Finish External		31.51	Pb	4.73	15.01	150111
			Sn	26.78	84.98	849889
			Sub-total:	31.51	99.99	1000000
Lead Finish Internal		1.15	Ag	1.15	100.00	1000000
			Sub-total:	1.15	100.00	1000000
Leadframe	OLIN 7025	270.80	Cu	260.51	96.20	962001
			Mg	0.41	0.15	1514
			Ni	8.12	2.99	29985
			Si	1.76	0.64	6499
			Sub-total:	270.80	99.98	999999
Marking Ink	Teca 261	0.10		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound	EME 6600CS	1286.22	Antimony Trioxide	25.72	1.99	19997
			Bromine	7.72	0.60	6002
			Epoxy Resin	128.62	9.99	99998
			Phenol Resin	82.32	6.40	64001
			Silica Fused	1041.84	81.00	810001
			Sub-total:	1286.22	99.98	999999
Wires	MGM 7	2.40	Au	2.40	100.00	1000000
			Sub-total:	2.40	100.00	1000000
Total:		1606.48				

GENNUM CORPORATION

Mailing Address: P.O. Box 489, Stn. A, Burlington, Ontario, Canada L7R 3Y3
 Shipping Address: 970 Fraser Drive, Burlington, Ontario, Canada L7L 5P5
 Tel. +1 (905) 632-2996 Fax. +1 (905) 632-5946

www.gennum.com

The information contained in this document describes the homogeneous material composition of this product according to the definition set forth in the EU RoHS Directive 2002/95/EC. This information may have been derived from calculations based on information obtained from our suppliers. Gennum Corporation assumes no liability for any errors or omissions in this document. Gennum reserves the right to make changes to this document at any time without notice.